

 	EPC2012CENGR
	EPC
Image may be representation. See specs for product details.	TRANS GAN 200V 5A BUMPED DIE
	 EPC2012CENGR.pdf
	 Lead free / RoHS
	Compliant New original, 2650 pcs Stock Available.
	Hong Kong
DHL/Fedex/TNT/UPS/EMS	

Specifications

Part Number	EPC2012CENGR
Manufacturer	EPC
Description	TRANS GAN 200V 5A BUMPED DIE
Category	Discrete Semiconductor Products > Transistors - FETs,
Part Status	2650 pcs Stock
Vgs(th) (Max) @ Id	2.5V @ 1mA
Technology	GaNFET (Gallium Nitride)
Supplier Device Package	Die Outline (4-Solder Bar)
Series	eGaN®
Rds On (Max) @ Id, Vgs	100 mOhm @ 3A, 5V
Power Dissipation (Max)	-
Packaging	Tape & Reel (TR)
Package / Case	Die
Operating Temperature	-40°C ~ 150°C (TJ)
Mounting Type	Surface Mount
Input Capacitance (Ciss) (Max) @ Vds	100pF @ 100V
Gate Charge (Qg) (Max) @ Vgs	1nC @ 5V
FET Type	N-Channel
FET Feature	-
Drain to Source Voltage (Vdss)	200V
Current - Continuous Drain (Id) @ 25°C	5A (Ta)

You May Be Also Be interested

In:  EPC2010C EPC TRANS GAN 200V 22A BUMPED DIE	 EPC2014 EPC TRANS GAN 40V 10A BUMPED DIE	 EPC2015 EPC TRANS GAN 40V 33A BUMPED DIE	 EPC2010CENGR EPC TRANS GAN 200V 22A BUMPED DIE
 EPC2010CENGR EPC TRANS GAN 200V 22A BUMPED DIE	 EPC2012CENGR EPC TRANS GAN 200V 5A BUMPED DIE	 EPC2012 EPC TRANS GAN 200V 3A BUMPED DIE	 EPC2014C IC EPC EPC SMD

EPC2012CENGR Related keyword

More

EPC2012CENGR EPC	EPC2012CENGR Data Sheet	EPC2012CENGR Datasheets	EPC2012CENGR PDF	EPC EPC2012CENGR
EPC2012CENGR Electronic	EPC2012CENGR Components	EPC2012CENGR Distributor	EPC2012CENGR Image	EPC2012CENGR Part
EPC2012CENGR Price	EPC2012CENGR Manufacturer	EPC2012CENGR Picture	EPC2012CENGR Stock	EPC2012CENGR Inventory
EPC2012CENGR New	EPC2012CENGR Original	EPC2012CENGR Warranted	EPC2012CENGR RFQ	EPC2012CENGR Order Online